

CP Series 導熱絕緣帽套 Thermal Cap



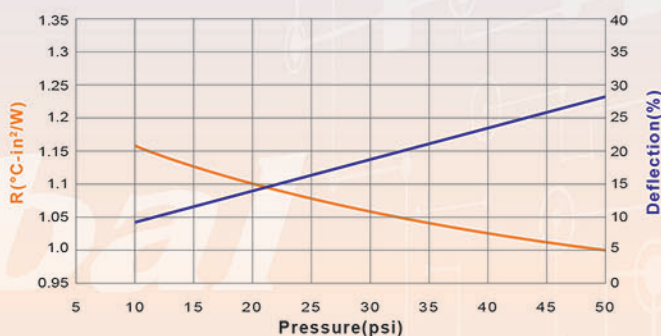
產品特性 Features

- Low thermal contact resistance 低熱阻抗
- Electrically isolating 高絕緣性
- Decrease the weight of the product 降低產品重量
- Easy to assemble 簡易安裝組件
- Thermal conduction and buffer effect 熱傳導與緩衝效果

產品應用端 Applications

- Electronic components: IC, CPU, MOS, LED,
- Mother Board, Power Supply, Heat Sink, LCD-TV,
- Notebook, PC, Telecom Device, Wireless Hub,
- DDR II Module, DVD Applications, Hand-set applications etc.

熱阻抗VS.壓力VS.變形量示意圖 Thermal Resistance VS. Pressure VS. Deflection



Pressure(psi)	R(°C-in ² /W)	Deflection(%)
10	1.16	9
20	1.1	14
50	1	28

選擇尺寸 Standard Sizes (mm)

1. CP22 TO-220: 11.4 x 16 x 5.8
2. CP23 TO-220: 11.4 x 21.5 x 5.8
3. CP33 TO-247: 17.5 x 28.5 x 5.8

Testing sample thickness: 0.45mm

In "Thermal resistance V.S. Pressure V.S. Deflection" chart, CP Series provides low thermal impedance. The pressure gets higher, the thermal impedance gets lower. CP Series provides good compliance and softness.

Hardness 軟硬度 : 75 (Shore A)



Properties	CP22/CP23/CP33	Unit	Tolerance	Test Method
Thermal Conductivity 導熱係數	1.9	W / mK	±0.19	ASTM D5470
Thickness 厚度	0.3/0.45	mm	-	ASTM D374
Color 顏色	Gray灰	-	-	Visual目視
Material 材料	Silicone	-	-	-
Working Temperature 工作溫度	-45~180	°C	-	-
Density 密度	2.55	g / cm ³	-	ASTM D792
Breakdown Voltage AC 耐電壓值	4/6	KV	±0.4/±0.6	ASTM D149
Breakdown Voltage DC 耐電壓值	6/8	KV	±0.6/±0.8	ASTM D149
Dielectric Constant 介電係數	5.8	1000Hz	-	ASTM D150
Thermal Impedance @10psi熱阻抗	1.16	°Cin ² / W	-	ASTM D5470
Thermal Impedance @20psi熱阻抗	1.1	°Cin ² / W	-	ASTM D5470
Thermal Impedance @50psi熱阻抗	1	°Cin ² / W	-	ASTM D5470
Hardness 硬度	75	Shore A	±7	ASTM D2240